



SOT2143-1

HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm

4 January 2022

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON12
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-05-2021
Manufacturer package code	98ASA01793D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3	-	mm
package width	-	3	-	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	12	-	



HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm
 x 3 mm x 0.85 mm

2 Package outline

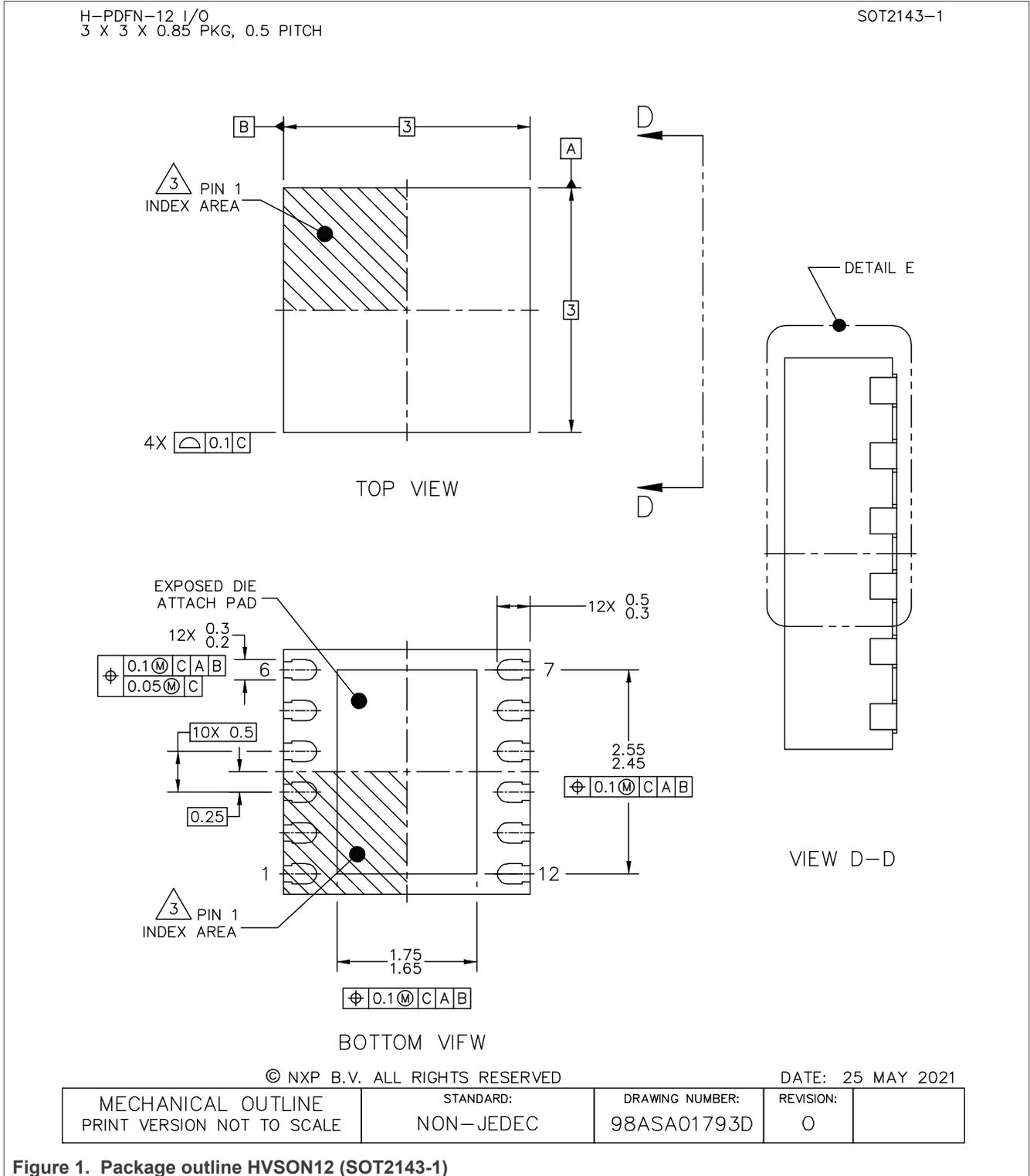
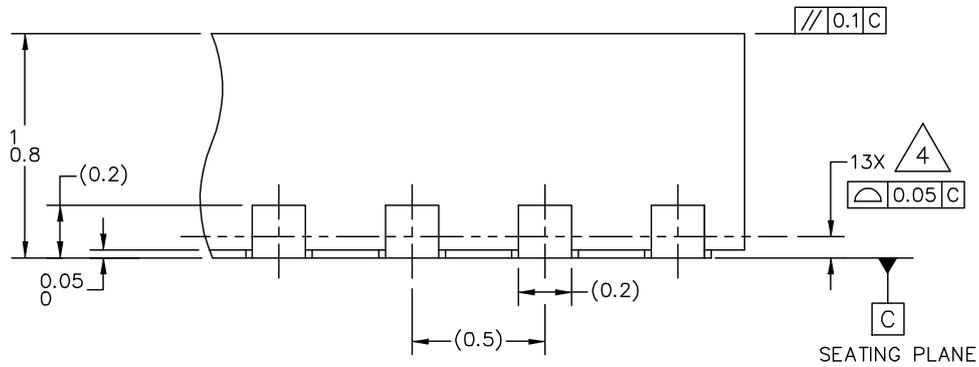


Figure 1. Package outline HVSON12 (SOT2143-1)

HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm

H-PDFN-12 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT2143-1



DETAIL E
VIEW ROTATED 90° CW

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DATE: 25 MAY 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01793D	REVISION: 0	
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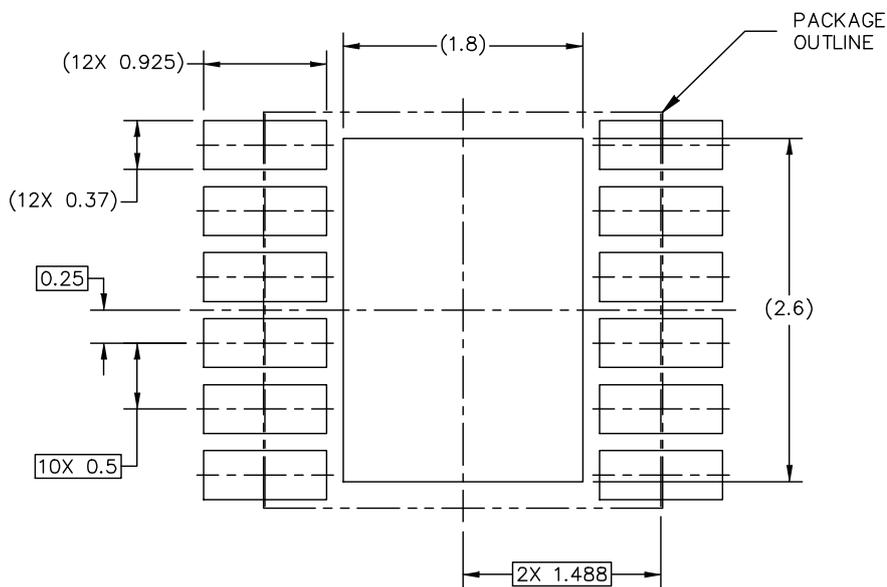
Figure 2. Package outline detail E of HVSON12 (SOT2143-1)

HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm

3 Soldering

H-PDFN-12 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

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PCB DESIGN GUIDELINES
RECOMMENDED SOLDER MASK OPENING PATTERN

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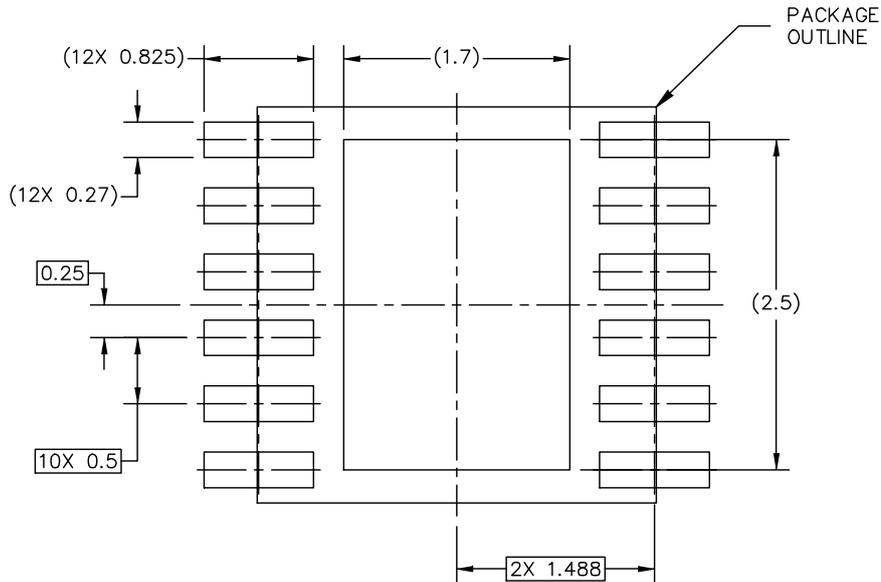
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Figure 3. Reflow soldering footprint part1 for HVSON12 (SOT2143-1)

HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm

H-PDFN-12 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

SOT2143-1



PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

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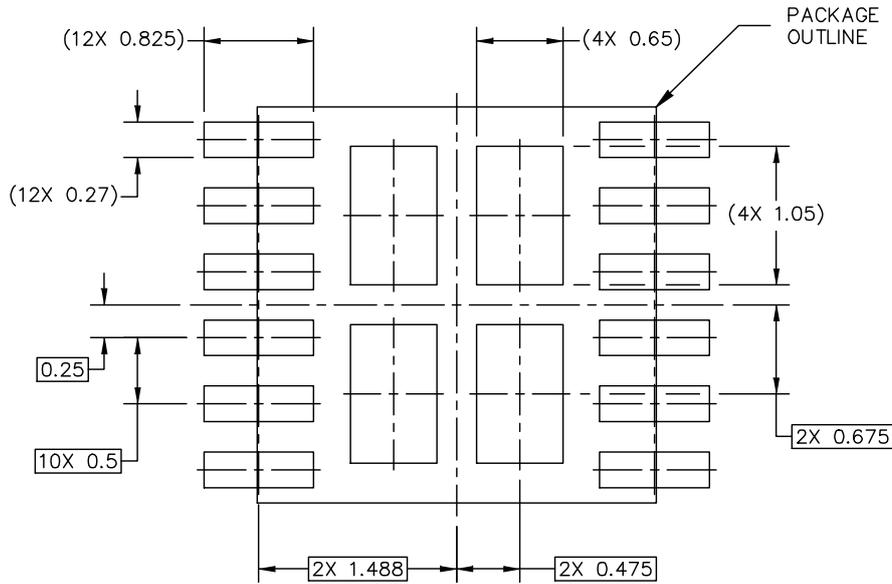
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Figure 4. Reflow soldering footprint part2 for HVSON12 (SOT2143-1)

HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm

H-PDFN-12 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

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RECOMMENDED STENCIL THICKNESS 0.125 OR 0.150

PCB DESIGN GUIDELINES – RECOMMENDED SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HVSON12 (SOT2143-1)

HVSON12, plastic thermal enhanced very thin small outline package; no leads; 12 terminals; body 3 mm x 3 mm x 0.85 mm

H-PDFN-12 I/O
3 X 3 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVSON12 (SOT2143-1)

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x 3 mm x 0.85 mm

4 Legal information

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x 3 mm x 0.85 mm

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